

Without SIPR-PR1

Cu Sputtered Substrate

Resist - SIPR 9270

Thickness - 6.4um

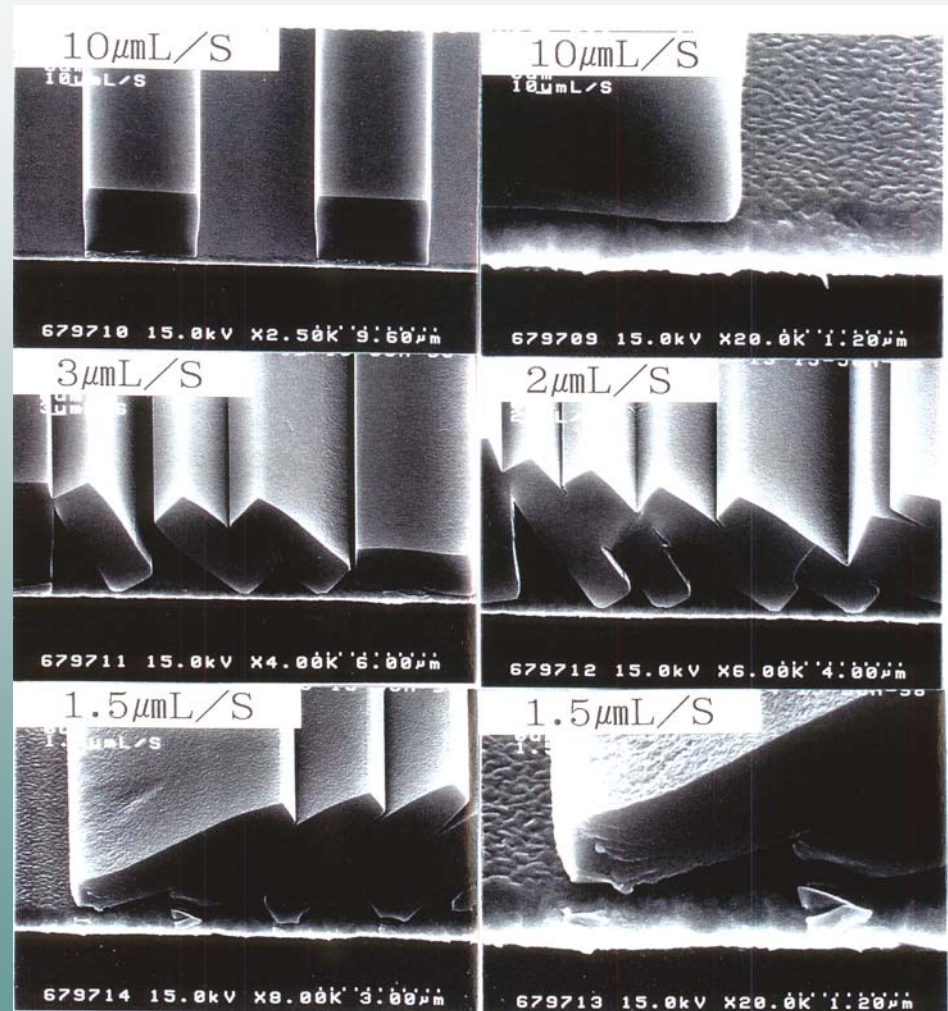
PAB - 80°C for 120sec

Exp - 630mJ (i-line, NA= 0.50, $\sigma = 0.60$)

Mask - 10~1.5um L/S

PEB - None

Dev - 50sec x 3 puddles (SSFD-238)



With SIPR-PR1

Cu Sputtered Substrate

Resist - SIPR 9270

Thickness - 6.4 μ m

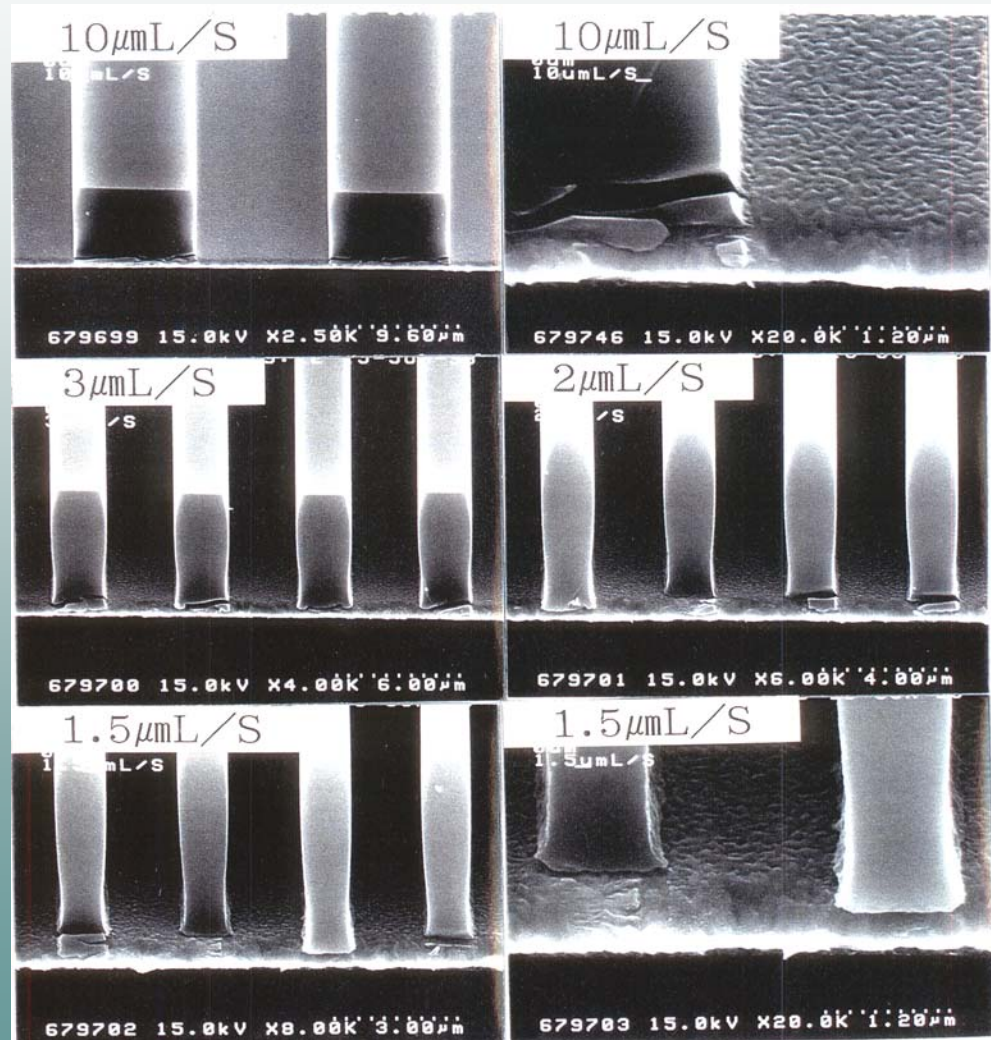
PAB - 80°C for 120sec

Exp - 630mJ (i-line, NA= 0.50, σ = 0.60)

Mask - 10~1.5 μ m L/S

PEB - None

Dev - 50sec x 3 puddles (SSFD-238)



With and Without SIPR-PR1 – Aged

Cu Sputtered Substrate

Resist - SIPR 9270

Thickness - 6.4um

PAB - 80°C for 120sec

Exp - 550, 625mJ (i-line, NA= 0.50, $\sigma = 0.60$)

Mask - 10~1.5um L/S

PEB - None

Dev - 50sec x 3 puddles (SSFD-238)

